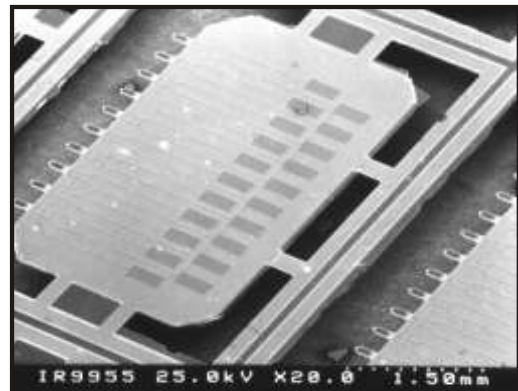
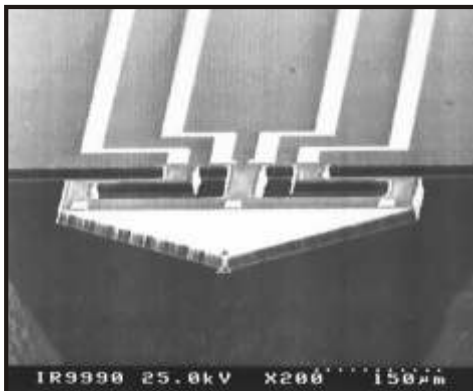
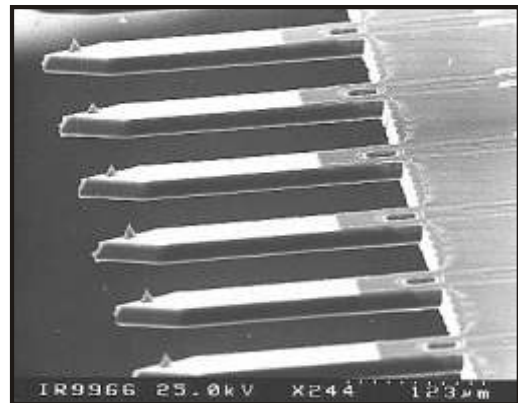


# Plasmalab Data

## ICP Si etching for AFM Microscopy

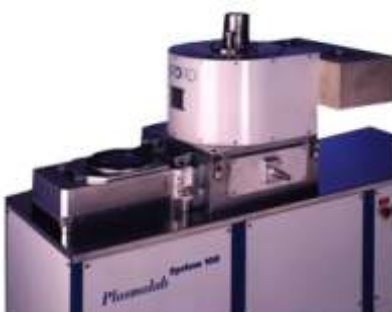


Etched at the OPT application lab, UK  
Courtesy of University of Kassel, Institute of  
Technical Physics, Dr. I. Rangelow

*Plasmalab 80 Plus*

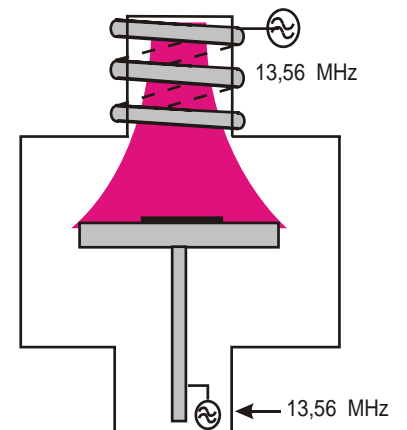
*Plasmalab System 100*

*Plasmalab System 133*



### Results:

Rate : ca. 1  $\mu\text{m}$  / min  
Profile: controllable  
two step process:  
anisotropic / isotropic  
uniform over a 4" wafer



### Technology:

Reactive Ion Etching (RIE)  
with Inductive Coupled Plasma  
Source (ICP)  
13.56 MHz Plasma Excitation  
Fluorine based Process